

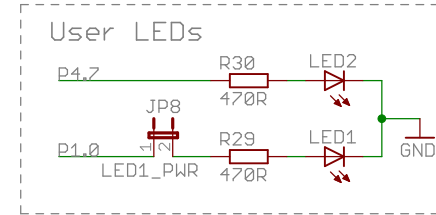
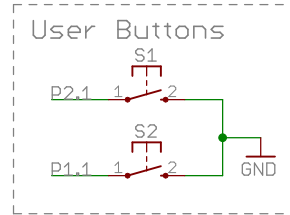
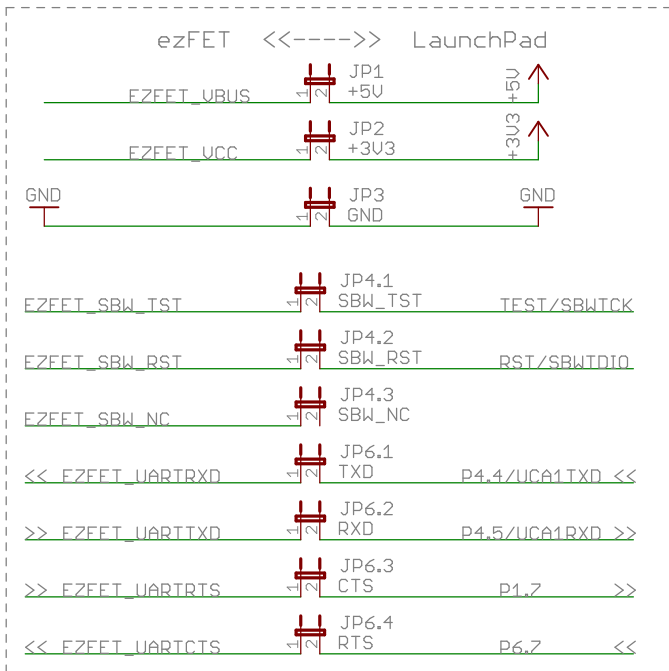
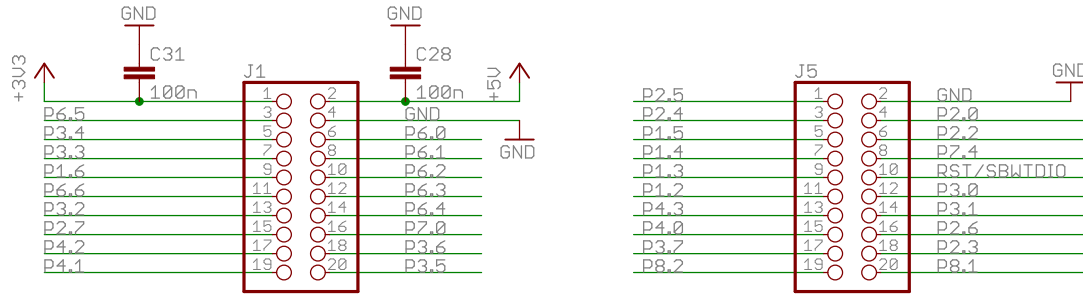
**Design Notes:**

- Remove R28 and inject AUCC directly if needed
- Free IO pins: 4.6, 5.0, 5.1, 5.6, 5.7, 7.1, 7.2, 7.3, 7.5, 7.6, 7.7, 8.0, PJ.x (<4)

Main MSP430F5529 w Power, Clock and USB	
TITLE: MSP-EXP430F5529LP	
Document Number:	REV: 1.6
Date: 7/27/2014 8:09:01 PM	Sheet: 1/4

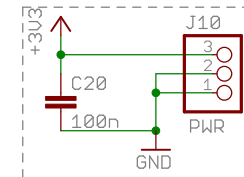
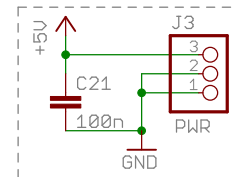


### 40 pin BoosterPack Headers



3V3

- U\$7 MOUNTHOLE\_125MIL
- U\$9 MOUNTHOLE\_125MIL
- U\$8 MOUNTHOLE\_125MIL
- U\$10 MOUNTHOLE\_125MIL



### Connections

TITLE: MSP-EXP430F5529LP

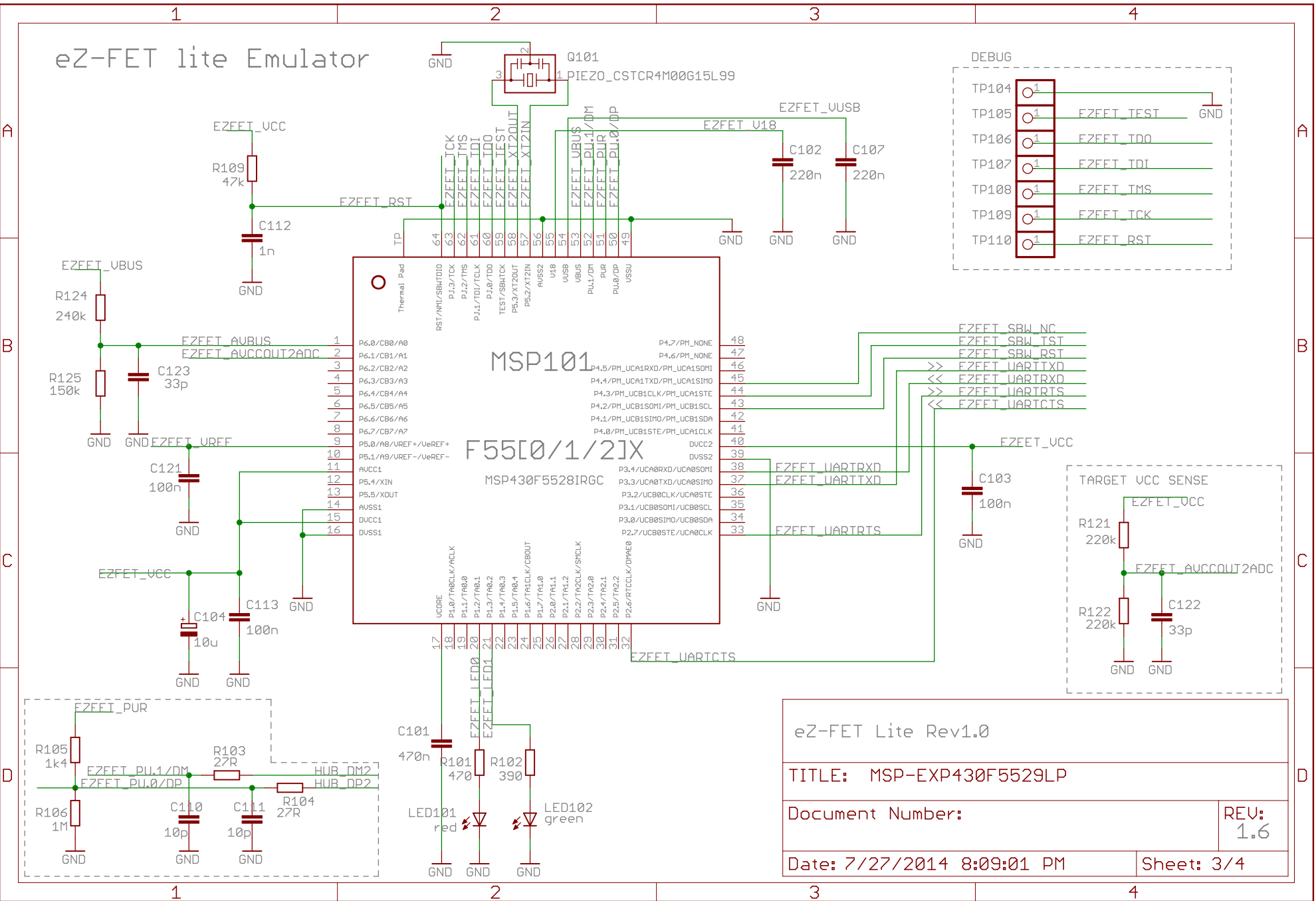
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# eZ-FET lite Emulator



eZ-FET Lite Rev1.0

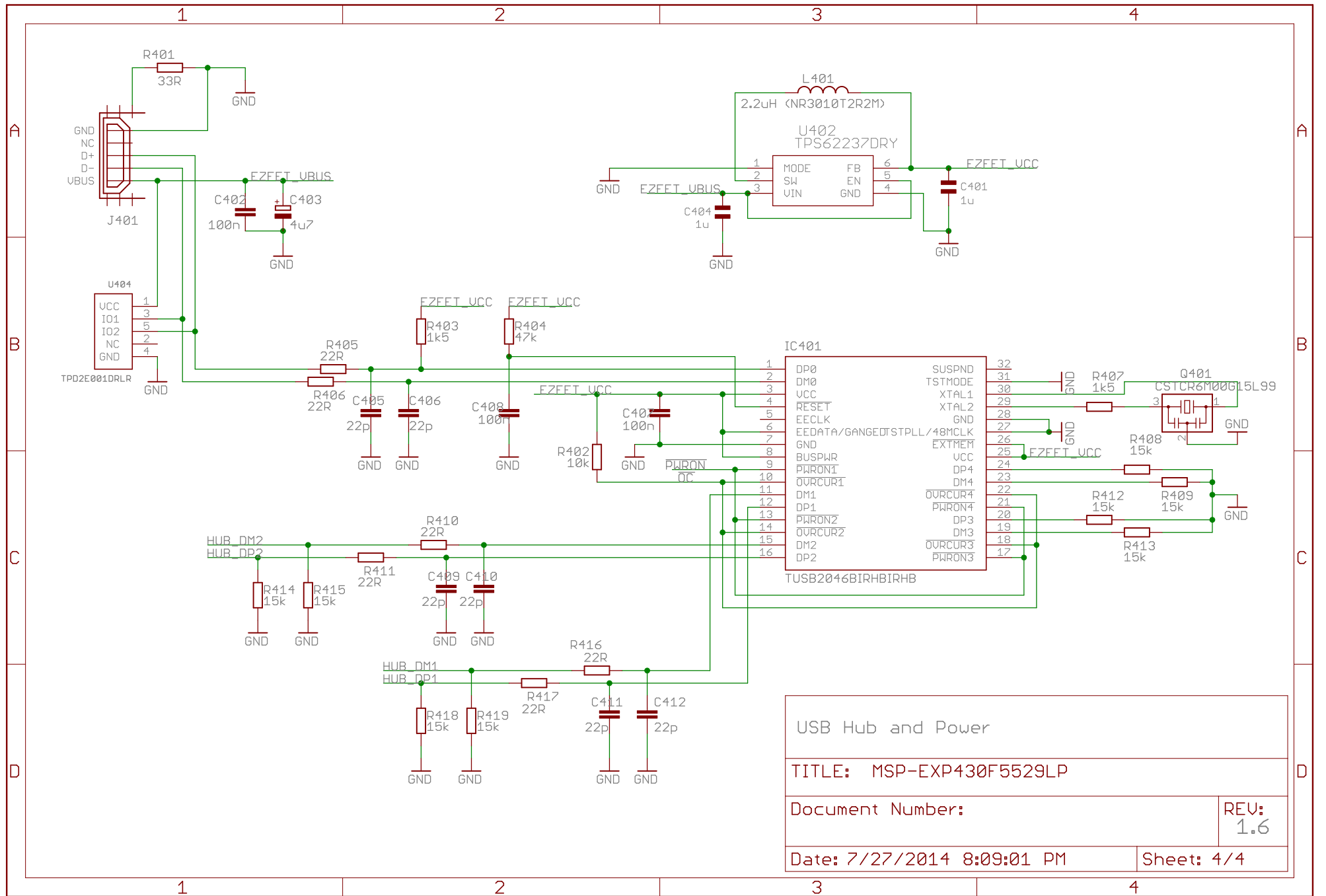
TITLE: MSP-EXP430F5529LP

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USB Hub and Power	
TITLE: MSP-EXP430F5529LP	
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